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Electronic Patent Application Submission
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EFS ID: 53688

Application ID: 10667227



Title of Invention:

SEMICONDUCTOR PACKAGE AND
METHOD OF MAKING
LEADFRAME HAVING LEAD
LOCKS TO SECURE LEADS TO
ENCAPSULANT

First Named Inventor: Jae Yee

Domestic/Foreign Application: Domestic Application

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Statement

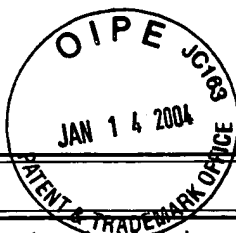
Filing Type:

Confirmation number: 7012

Attorney Docket Number: AMKOR012G1

Total Fees Authorized:


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Certificate Message Digest: 0f86bcea1c9109d6cdac92e6c19821ba894b963f

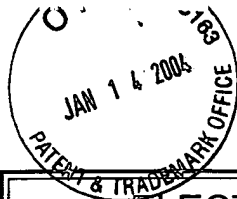


TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT									
Application Number: 10/667227 										
Date: 2003-09-18										
First Named Applicant: Jae Hak Yee										
Confirmation Number: 7012										
Attorney Docket Number: AMKOR012G1										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids2-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids2-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids2-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

SEMICONDUCTOR PACKAGE AND METHOD OF MAKING
LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS
TO ENCAPSULANT

Application Number: 10/667227



Confirmation Number: 7012

First Named Applicant: Jae Yee

Attorney Docket Number: AMKOR012G1

Art Unit: 2812

Search string: (5221642 or 5250841 or 5252853 or 5258094
or 5266834 or 5273938 or 5278446 or 5277972
or 5279029 or 5281849 or 5294897 or 5327008
or 5332864 or 5336931 or 5335771 or 5343076
or 5358905 or 5365106 or 5381042 or 5391439
or 5406124 or 5410180 or 5414299 or 5424576
or 5428248 or 5435057 or 5444301 or 5452511
or 5454905 or 5474958 or 5484274 or 5493151
or 5508556 or 5517056 or 5521429 or 5528076
or 5534467 or 5539251 or 5543657 or 5545923
or 5544412 or 5581122 or 5592025 or 5592019
or 5594274 or 5595934 or 5604376 or 5608267
or 5625222 or 5633528).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5221642	1993-06-22	BURNS			
	2	5250841	1993-10-05	SLOAN ET AL.			
	3	5252853	1993-10-12	MICHII			
	4	5258094	1993-11-02	FURUI ET AL.			
	5	5266834	1993-11-30	NISHI ET AL.			
	6	5273938	1993-12-28	LIN ET AL.			
	7	5278446	1994-01-11	NAGARAJ ET AL.			
	8	5277972	1994-01-11	SAKUMOTO ET AL.			

	9	5279029	1994-01-18	BURNS
	10	5281849	1994-01-25	SINGH DEO ET AL.
	11	5294897	1994-03-15	NOTANI ET AL.
	12	5327008	1994-06-05	DJENNAS ET AL.
	13	5332864	1994-07-26	LIANG ET AL.
	14	5336931	1994-08-09	JUSKEY ET AL.
	15	5335771	1994-08-09	MURPHY
	16	5343076	1994-08-30	KATAYAMA ET AL.
	17	5358905	1994-10-25	CHIU
	18	5365106	1994-11-15	WATANABE
	19	5381042	1995-01-10	LERNER ET AL.
	20	5391439	1995-02-21	TOMITA ET AL.
	21	5406124	1995-04-11	MORITA ET AL.
	22	5410180	1995-04-25	FUJII ET AL.
	23	5414299	1995-05-09	WANG ET AL.
	24	5424576	1995-06-13	DJENNAS ET AL.
	25	5428248	1995-06-27	CHA
	26	5435057	1995-07-25	BINDRA ET AL.
	27	5444301	1995-08-22	SONG ET AL.
	28	5452511	1995-09-26	CHANG
	29	5454905	1995-10-03	FOGELSON
	30	5474958	1995-12-12	DJENNAS ET AL.
	31	5484274	1996-01-16	NEU
	32	5493151	1996-02-20	ASADA ET AL.
	33	5508556	1996-04-16	LIN
	34	5517056	1996-05-14	BIGLER ET AL.
	35	5521429	1996-05-28	AONO ET AL.
	36	5528076	1996-06-18	PAVIO
	37	5534467	1996-07-09	ROSTOKER
	38	5539251	1996-07-23	IVERSON ET AL.
	39	5543657	1996-08-06	DIFFENDERFER ET AL.
	40	5545923	1996-08-13	BARBER
	41	5544412	1996-08-13	ROMERO ET AL.
	42	5581122	1996-12-03	CHAO ET AL.
	43	5592025	1997-01-07	CLARK ET AL.
	44	5592019	1997-01-07	UEDA ET AL.

	45	5594274	1997-01-14	SUETAKI
	46	5595934	1997-01-21	KIM
	47	5604376	1997-02-18	HAMBURGEN ET AL.
	48	5608267	1997-03-04	MAHULIKAR ET AL.
	49	5625222	1997-04-29	YONEDA ET AL.
	50	5633528	1997-05-27	ABBOTT ET AL.

Signature

Examiner Name	Date